

HVC379B

Variable Capacitance Diode for VCO

REJ03G0492-0100

(Previous: ADE-208-817)

Rev.1.00 Jan 19, 2005

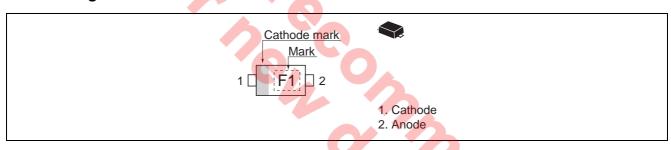
Features

- High capacitance ratio. (n = 1.80 min)
- Low series resistance. (rs = $1.0 \Omega \text{ max}$)
- Ultra small Flat Lead Package (UFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HVC379B	F1	UFP

Pin Arrangement



50.00

Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

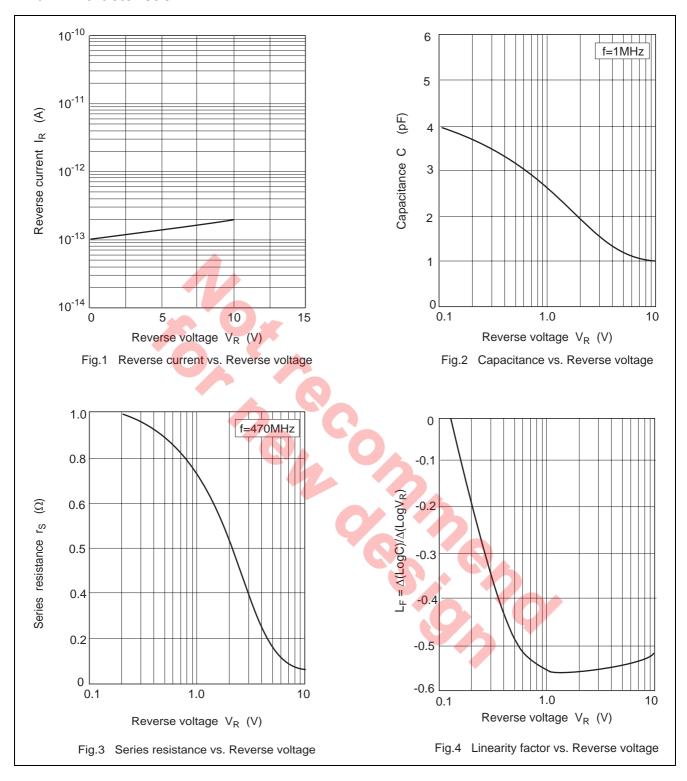
Item	Symbol	Value	Unit
Reverse voltage	V_R	10	V
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Electrical Characteristics

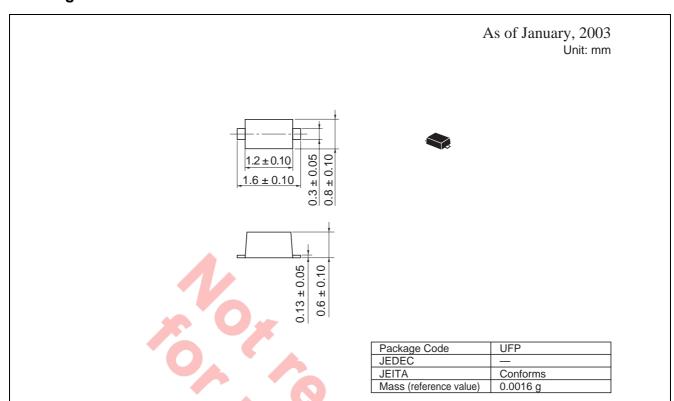
 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I _{R1}	_	_	10	nA	V _R =10 V
	I _{R2}	_	_	100		V _R = 10 V, Ta = 60°C
Capacitance	C _{0.5}	2.90	_	3.20	pF	V _R = 0.5 V, f = 1 MHz
	C _{2.5}	1.25	_	1.53		V _R = 2.5 V, f = 1 MHz
Capacitance ratio	n	1.80	_	_	_	C _{0.5} / C _{2.5}
Series resistance	rs		_	1.0	Ω	V _R = 1 V, f = 470 MHz

Main Characteristic



Package Dimensions



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Renesas Technology America, Inc. 450 Holger Way, San Jose, CA 95134-1368, U.S.A Tel: <1> (408) 382-7500, Fax: <1> (408) 382-7501

Renesas Technology Europe Limited
Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K. Tel: <44> (1628) 585-100, Fax: <44> (1628) 585-900

Renesas Technology Hong Kong Ltd.
7th Floor, North Tower, World Finance Centre, Harbour City, 1 Canton Road, Tsimshatsui, Kowloon, Hong Kong Tel: <852> 2265-6688, Fax: <852> 2730-6071

Renesas Technology Taiwan Co., Ltd. 10th Floor, No.99, Fushing North Road, Taipei, Taiwan Tel: <886> (2) 2715-2888, Fax: <886> (2) 2713-2999

Renesas Technology (Shanghai) Co., Ltd. Unit2607 Ruijing Building, No.205 Maoming Road (S), Shanghai 200020, China Tel: <86> (21) 6472-1001, Fax: <86> (21) 6415-2952

Renesas Technology Singapore Pte. Ltd.
1 Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632 Tel: <65> 6213-0200, Fax: <65> 6278-8001